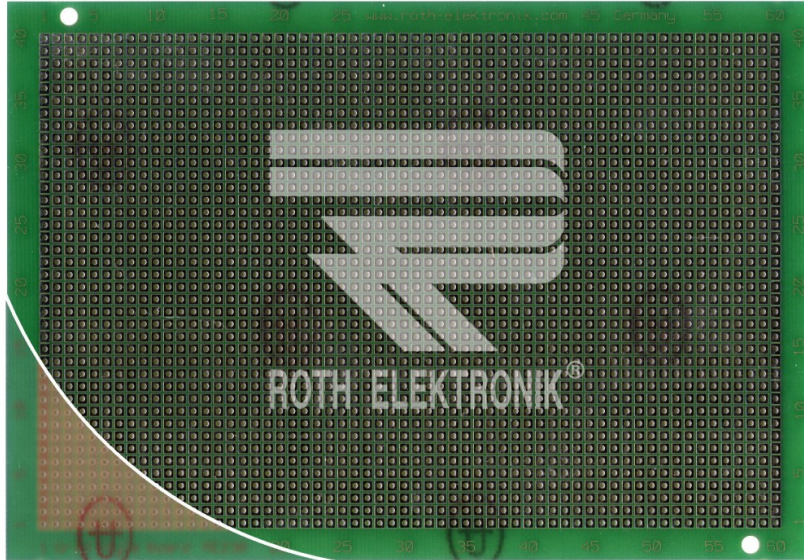


**Prototyping Board (not in Europe-format)**



**RE230-LF**

- EPOXY fibre-glass FR4 1.60 mm single-sided 35 µm CU
- hot air leveling (HAL-leadfree) with soldering stop mask
- hole spacing 2.54 mm x 2.54 mm (1/20")
- 40 x 60 tracks of bored holes
- 40 x 58 square lands 2.00 mm<sup>2</sup>
- hole dia 1.02 mm (0.40")
- max working temperature 150° C (302° F)
- size 114.30 mm x 165.10 mm (4.5" x 6.5")